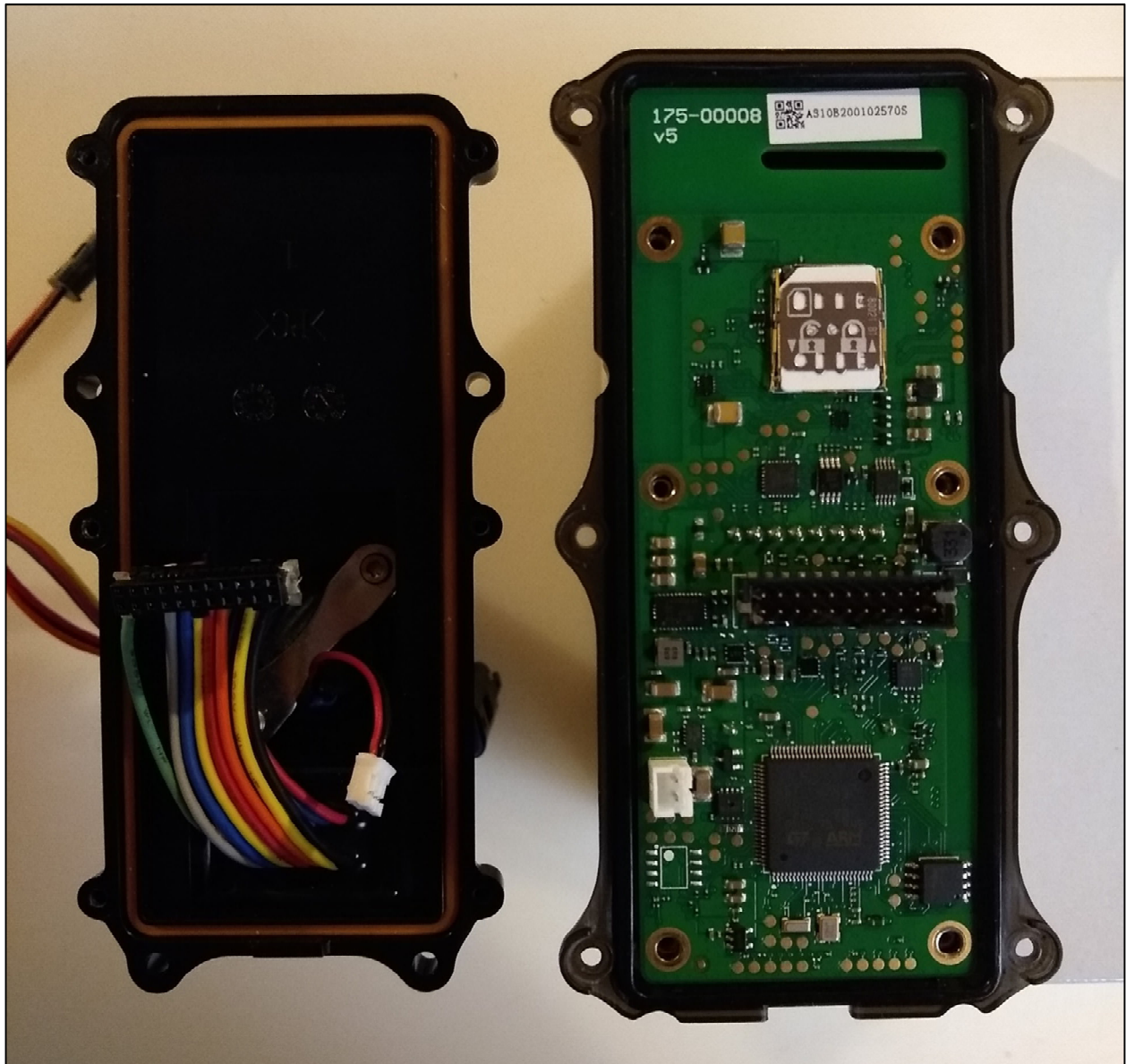
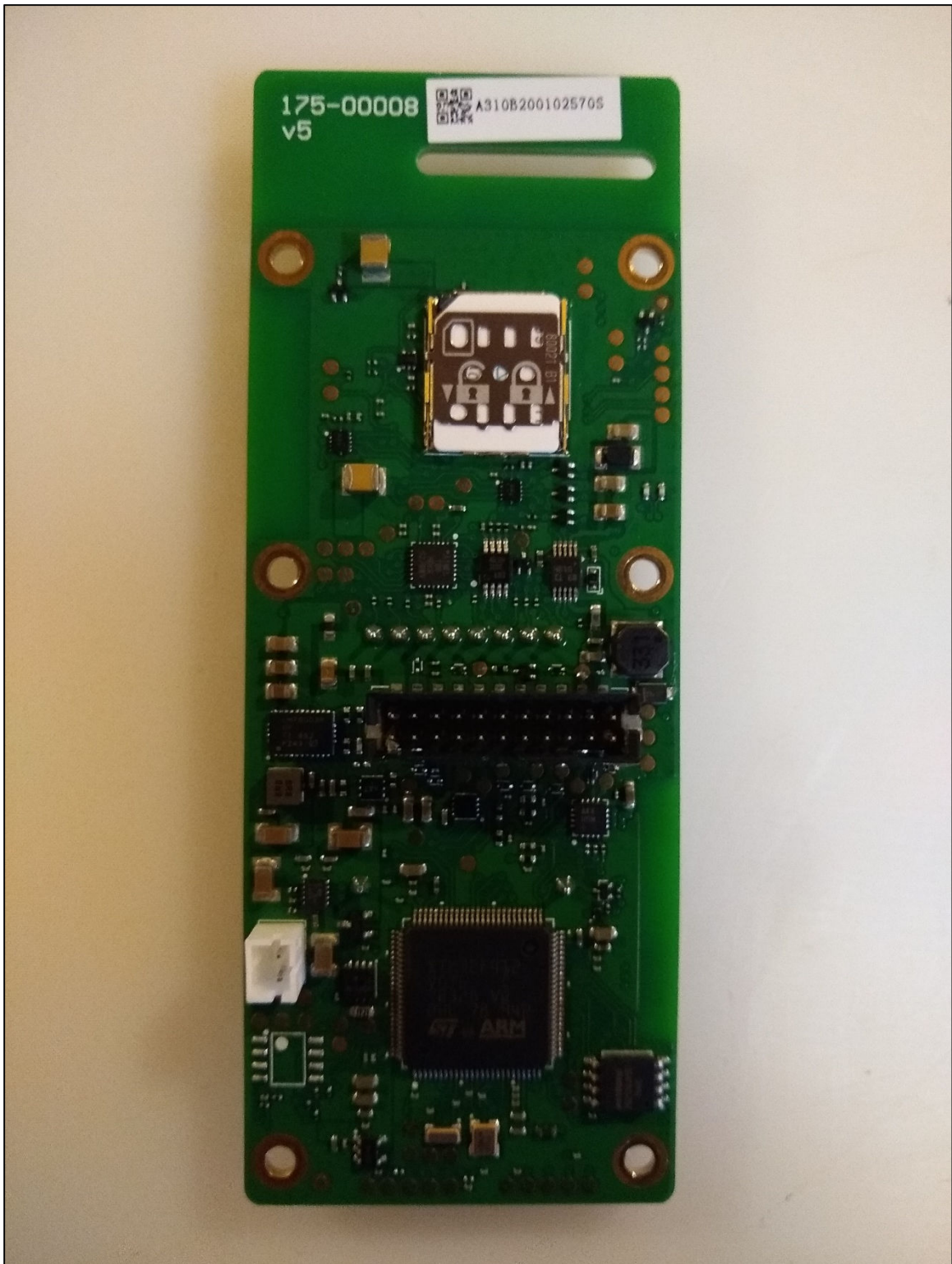
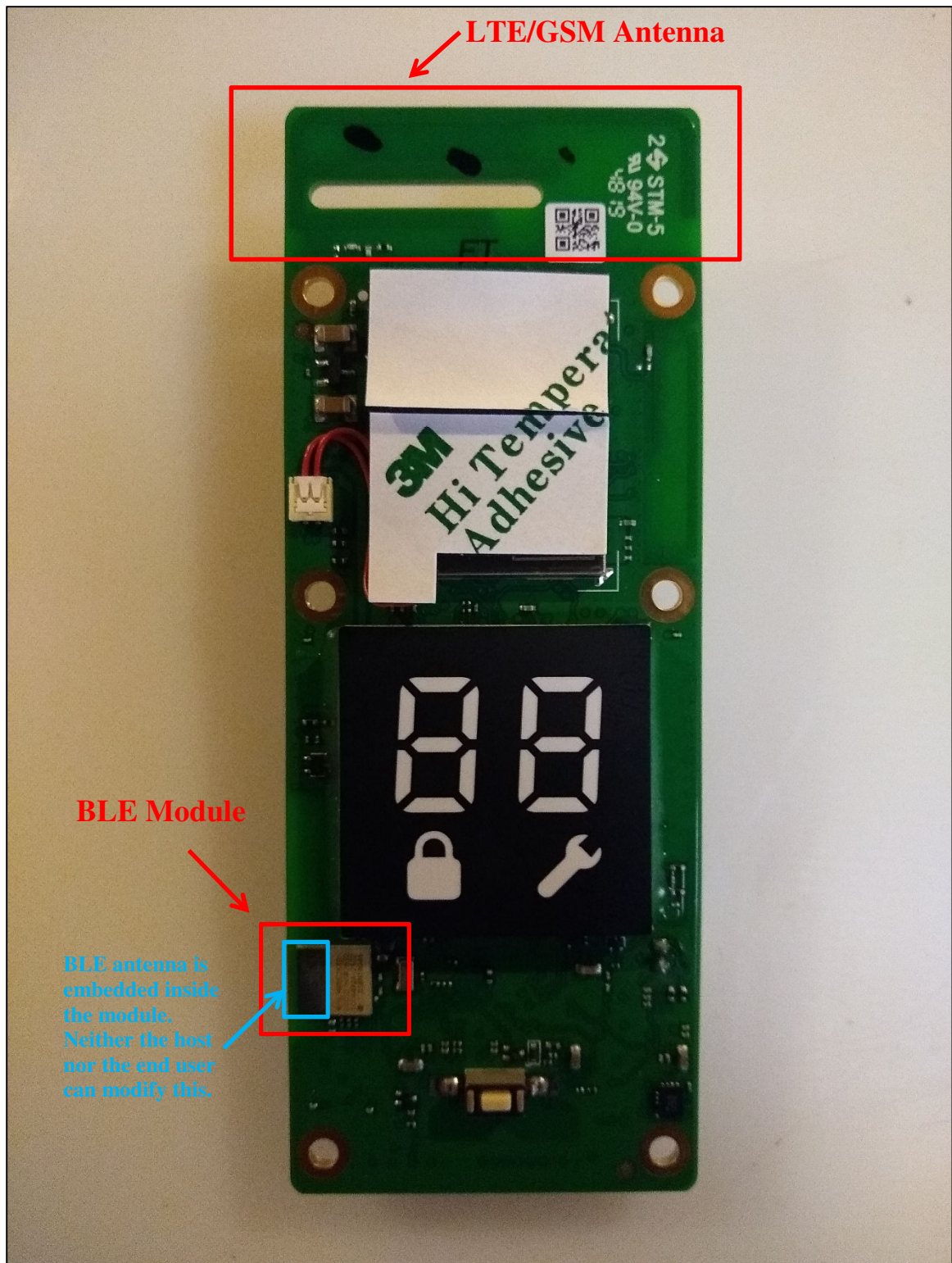




Photograph 1. Outer Cover Removed



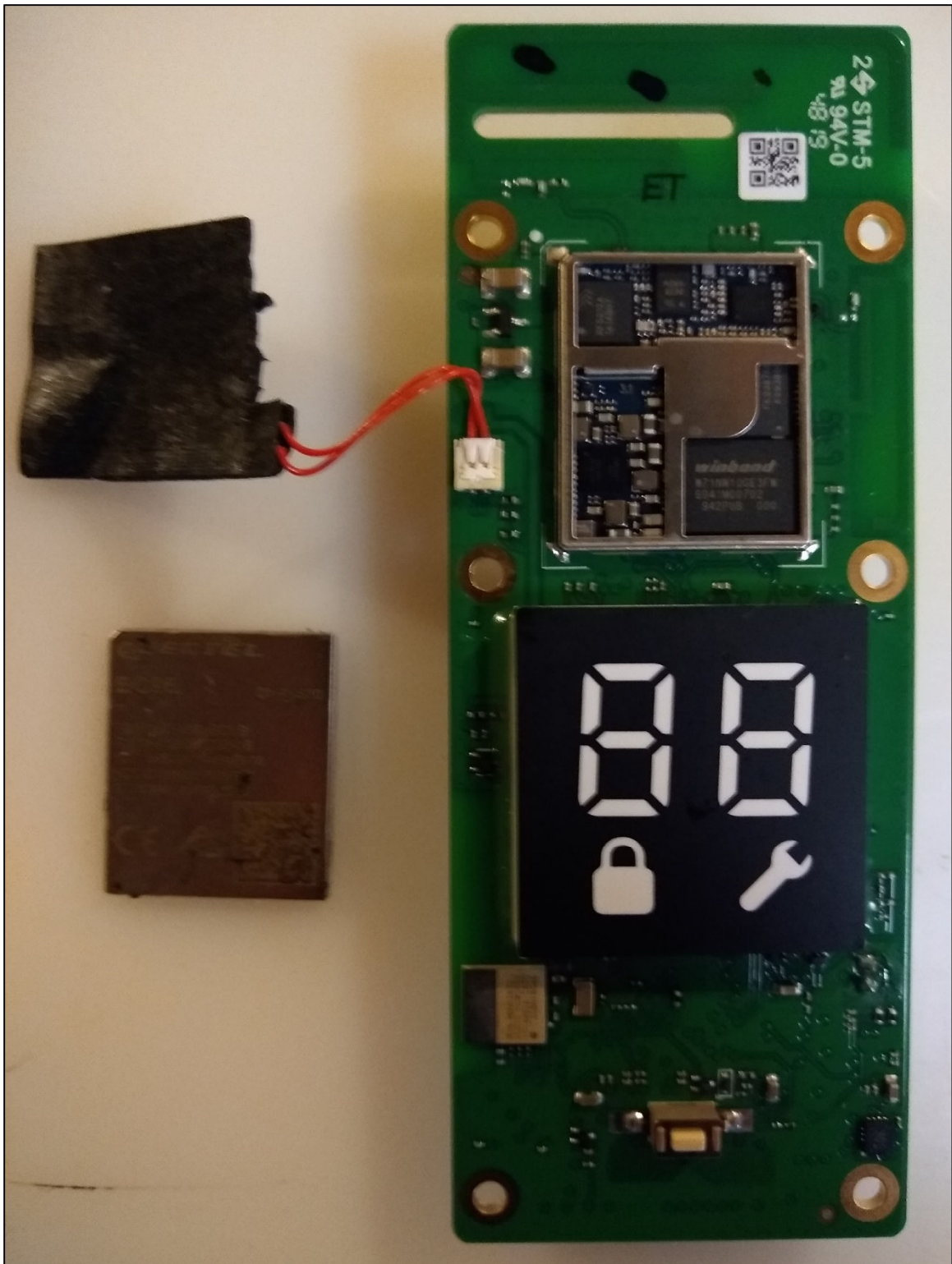
Photograph 2. PCB – Back Side



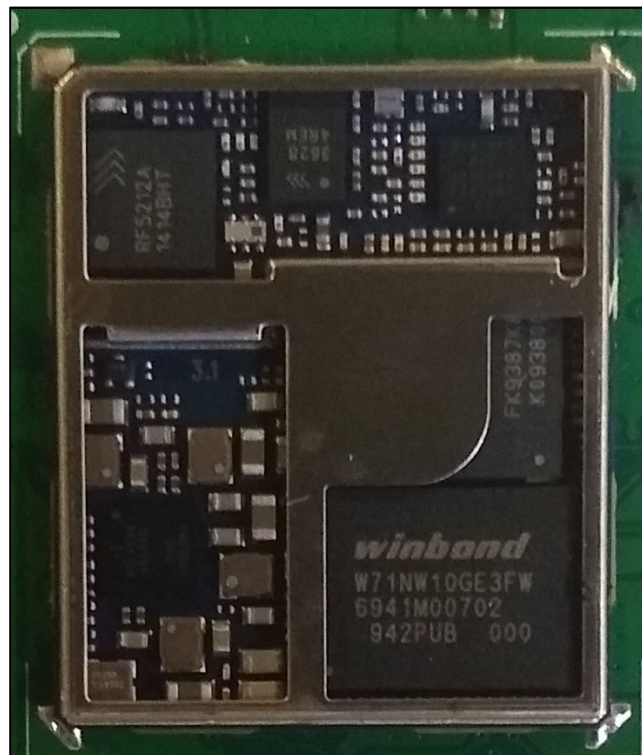
Photograph 3. PCB – Front Side



Photograph 4. PCB – Heat sensor removed to show Quectel BG96-MC module.



Photograph 5. Quectel BG96-MC module shield cover removed.



Photograph 6. Quectel BG96-MC module close-up.



Photograph 7. BLE module close-up.



Photograph 8. ARM processor close-up.